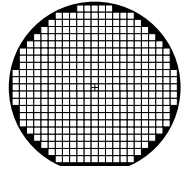




# DUMMY WAFERS MECHANICAL GRADE SPECIFICATION FORM



Name \_\_\_\_\_ email \_\_\_\_\_

Company \_\_\_\_\_ Customer Ref \_\_\_\_\_

1. Application
  - Dicing Practice
  - Vision Recognition
  - Placement Machine
  - Other \_\_\_\_\_
2. Wafer Diameter
  - 4"       5"       6"
  - 8"       12"
3.  Mirrored Polish Mechanical  
    Dummy Wafer without Die Pattern  
 Wafer with Die Pattern
4. Sawing (Dicing)
  - Required
  - Not Required
5. Die          WIDE     x     LONG              THICK      
Size Max \_\_\_\_\_ x \_\_\_\_\_       mil  mm  
Size Min \_\_\_\_\_ x \_\_\_\_\_       mil  mm
6. Packaging/Mounting
  - UV Tape for Diced Wafer
  - Coin Rolled in Jar for Mirror Wafer
  - Cassette
  - Other \_\_\_\_\_
7. Quantity Wafers \_\_\_\_\_
8. Notes \_\_\_\_\_

Note: Approximate Prime Wafer Thickness  
Before Back Grinding (± 25mm)

4" = 525µm    6" = 725µm  
5" = 625µm    8" = 825µm  
12" = 700 ~ 800µm

### Part Numbering System

<b>WDIE    6    -    5.18 x 6.73    -    UV</b>	
<b>Wafer Type</b> WAFER= Wafer mirrored  WDIE = Wafer with die chip pattern  DIE = Single Die	<b>Die Size (mm)</b> Width x Length Blank = mirror wafer  <b>Mounting &amp; Pack</b>  UV = tape & ring WP2 = 2" waffle pack WP4 = 4" waffle pack J = Jar coin rolled with foam C = Cassette
<b>Diameter</b>  3 = 75mm 4 = 100mm 5 = 125mm 6 = 150mm 8 = 200mm 12 = 300mm Blank if Die	